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最終頁に続く

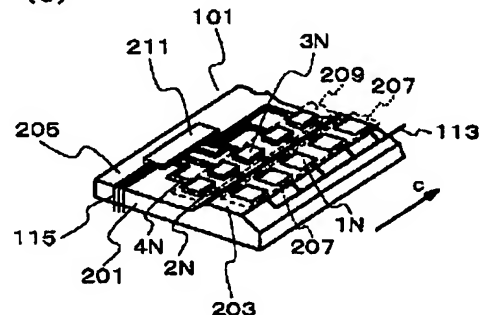
(54) 【発明の名称】 薄型表示装置用電極構造体の検査装置及びその検査方法

(57) 【要約】

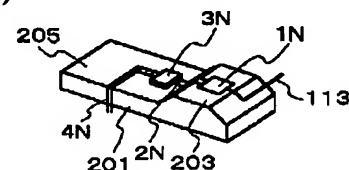
【課題】 検査の高速化及び高精度化を可能にする薄型表示装置用電極構造体の検査装置、及びその検査方法を提供する。

【解決手段】 本発明の薄型表示装置用電極構造体の検査装置、及びその検査方法は、複数の画素電極の各々に電界効果トランジスタ機能を有する電位センサを静電結合させて前記各々の画素電極に生じる画素電圧を検出し、検出した前記画素電圧に基づいて前記画素電極の異常を判定する事の特徴とする。

(a)



(b)



(2)

特開2000-55964

1

2

## 【特許請求の範囲】

【請求項1】 複数の画素電極の各々に電界効果トランジスタ機能を有する電位センサを静電結合させて前記各々の画素電極に生じる画素電圧を検出し、検出した前記画素電圧に基づいて前記画素電極の異常を判定する事を特徴とする薄型表示装置用電極構造体の検査方法。

【請求項2】 画素電極に静電結合する電界効果トランジスタ機能を利用して、前記画素電極に生じる画素電圧を検出する1つ以上の電位センサをアンプに接続し、前記アンプをスキュナに接続してなる事を特徴とする請求項1記載の薄型表示装置用電極構造体の検査方法を実施する検査装置。

【請求項3】 薄型表示装置用電極構造体を検査する為の検査部と、前記検査部には、FET機能を利用した電位センサが複数個配置され、

第1の信号にตอบสนองして、前記薄型表示装置用電極構造体と、前記検査部の少なくとも一部とを、第1の間隔を保持した状態で、画素電極の配置に関し、相対的に移動させる為の駆動部と、前記薄型表示装置用電極構造体は、 $n$ 行 $m$ 列( $n$ 、 $m$ は自然数)に行列配置される前記画素電極を収容し、又、複数の前記電位センサの配置方向と、前記画素電極の前記行列配置における行又は列方向とは一致しており、

検査対象である画素電極の検査報告を示す第4の信号にตอบสนองして、前記第1の信号を出力し、前記薄型表示装置用電極構造体と、前記検査部の少なくとも一部が、1行又は1列分だけ相対的に移動した時に、被検査開始命令を示す第2の信号と、検査開始命令を示す第3の信号とを出力する為の制御部とから成り、

現検査対象である画素電極、又は前記画素電極に隣接する画素電極が、前記第2の信号に順次ตอบสนองする事により、現検査対象である前記画素電極に順次画素電圧を生じ、前記現検査対象である前記画素電極に位置対向する現電位センサが、前記第3の信号にตอบสนองして、静電結合を利用して前記画素電圧を順次検出し、現検査対象である画素電極の検査報告を示す前記第4の信号を順次出力し、前記制御部が、前記第4の信号にตอบสนองして、次検査対象である画素電極、又は前記画素電極に隣接する画素電極に対して前記第2の信号を出力し、又、前記次検査対象である画素電極に位置対向する電位センサに対して、前記第3の信号を出力する事を特徴とする薄型表示装置用電極構造体の検査装置。

【請求項4】 FET機能を利用した電位センサと、ここに前記電位センサは、画素電極に生じる画素電圧を検出する為のゲート電極を備え、該電位センサと位置対向する画素電極と静電的に接続する事により、電位センサ信号を出力し、前記電位センサ信号を増幅して、アンプ信号を出力する為のアンプとから成る事を特徴とする薄型表示装置用電極構造体の検査装置。

## 【発明の詳細な説明】

【0001】

【発明の属する技術分野】本発明は、薄型表示装置用電極構造体に対する検査装置、及びその検査方法に関する。

【0002】

【従来の技術】薄型表示装置は、TV、パーソナルコンピュータ等のディスプレイをその用途として生産されている。この薄型表示装置用の電極構造体に対する評価方法としては動作試験、信頼性試験及び外観試験等がある。特に、従来の点灯動作確認試験については、製品として組立られた後に実施されている。

【0003】従来の薄型表示装置用電極構造体の検査方法を図8に示す。本従来例では、薄型表示装置用電極構造体を、液晶パネルを例にしている。尚、本明細書においては、薄型表示装置用電極構造体は、 $n$ 行 $m$ 列( $n$ 、 $m$ は整数)の行列要素として配置された画素電極を収容するものと定義する。

【0004】図8に示す検査方法は、ブローバ方式と呼ばれるものである。基板86上にゲート電圧配線83が設けられている。これらは、TFT型トランジスタ群の要素80の間に縦横に形成され、配置されている。

【0005】本検査方法は、ソース電圧配線85に、触針(ブローバ)81、82を各々接触させ、その出力電圧を検出する事により、画素電極84の断線、短絡等を検査する。つまり、薄型表示装置用電極構造体に形成されているゲート電圧配線83と、ソース電圧配線85に検査信号を印加することにより、画素電極84の欠陥を検出する。

【0006】

【発明が解決しようとする課題】このブローバ方式の検査方法は、薄型表示装置用電極構造体の大型化に伴い、触針の接触不良数が増加してその交換頻度が増大し、その結果維持費が増大するという問題に直面している。

【0007】液晶ディスプレイは、その表示情報の多量化に伴う大型化・フルカラー化、更にはその高精細化に併せて、画素ピッチの縮小化が要求されている。従って、検査装置の接触不良が起きず高速・高精度な検査を可能にする検査装置及びその検査方法が早急に提供される事が望まれている。

【0008】本発明の目的は、検査の高速化及び高精度化を可能にする薄型表示装置用電極構造体の検査装置、及びその検査方法を提供する事にある。

【0009】

【課題を解決するための手段】上記課題を解決する為に、本発明の薄型表示装置用電極構造体の検査装置及びその検査方法は、複数の画素電極の各々に電界効果トランジスタ機能を有する電位センサを静電結合させて前記各々の画素電極に生じる画素電圧を検出し、検出した前記画素電圧に基づいて前記画素電極の異常を判定する事

(3)

特開2000-55964

3

4

を特徴とする。

【0010】又、画素電極に静電結合する電界効果トランジスタ機能を利用して、前記画素電極に生じる画素電圧を検出する1つ以上の電位センサをアンプに接続し、前記アンプをスキュナに接続してなる事を特徴とする。

【0011】更に、薄型表示装置用電極構造体を検査する為の検査部と、前記検査部には、FET機能を利用した電位センサが複数個配置され、第1の信号にตอบสนองして、前記薄型表示装置用電極構造体と、前記検査部の少なくとも一部とを、第1の間隔を保持した状態で、画素電極の配置に関し、1行又は1列分だけ相対的に移動させる為の駆動部と、前記薄型表示装置用電極構造体は、 $n$ 行 $m$ 列( $n$ 、 $m$ は自然数)に行列配置される前記画素電極を收容し、又、複数の前記電位センサの配置方向と、前記行列配置における行又は列方向とは一致しており、前記検査対象である画素電極の検査報告を示す第4の信号にตอบสนองして、前記第1の信号を出力し、前記薄型表示装置用電極構造体と、前記検査部の少なくとも一部が、相対的に移動した時に、被検査開始命令を示す第2の信号と、検査開始命令を示す第3の信号とを出力する為の制御部とから成り、現検査対象である画素電極、又は前記画素電極に隣接する画素電極が、前記第2の信号に順次ตอบสนองする事により、現検査対象である前記画素電極に順次画素電圧を生じ、前記検査部において現電位センサが、前記第3の信号にตอบสนองして、静電結合を利用して前記画素電圧を順次検出し、現検査対象である画素電極の検査報告を示す前記第4の信号を順次出力し、前記制御部が、前記第4の信号にตอบสนองして、次検査対象である画素電極、又は前記画素電極に隣接する画素電極に対して前記第2の信号を出力し、又、前記次検査対象である画素電極に位置対向する電位センサに対して、前記第3の信号を出力する事を特徴とする事を特徴とする。

【0012】更に、FET機能を利用した電位センサと、ここに前記電位センサは、前記画素電極に生じる画素電圧を検出する為のゲート電極を備え、該電位センサと位置対向する画素電極と静電的に接続する事により、電位センサ信号を出力し、前記電位センサ信号を増幅して、アンプ信号を出力する為のアンプとから成る事を特徴とする。

【0013】

【発明の実施の形態】次に、本発明の薄型表示装置用電極構造体の検査装置及びその検査方法について、添付図面を参照して詳細に説明する。図1に、本発明である薄型表示装置用電極構造体の検査装置の実施の形態を示す。尚、本発明の実施の形態では薄型表示装置用電極構造体を、液晶パネルを例に説明する。

【0014】図1を参照して、本構成は薄型表示装置用電極構造体103を検査する為の検査部101と、駆動部105及び制御部107とから構成される。検査部101は、薄型表示装置用電極構造体103と間隔 $d$ (第

1の間隔)を保持して配置される。

【0015】薄型表示装置用電極構造体103は、 $n$ 行 $m$ 列( $n$ 、 $m$ は整数)の行列要素として配置された画素電極を收容している(図1では矢印の $a$ 方向と矢印の $b$ 方向に行列配置されている)。

【0016】制御部107は、検査部101から、検査対象である各画素電極の検査報告を示す第4の信号115にตอบสนองして、検査部101と薄型表示装置用電極構造体103とが、画素電極の行列配置に関して1行又は1列分だけ、相対的に移動させる為の第1の信号109を出力する。

【0017】後述するが、これは1行又は1列分の画素電極数に關係する、第4の信号115の入力回数を、制御部107がカウントする事等により対応する。

【0018】又、制御部107は、検査部101と薄型表示装置用電極構造体103とが、1行又は1列分だけ相対的に移動した時に、薄型表示装置用電極構造体103に対して、被検査開始命令を示す第2の信号111を与える。

【0019】後述するが、これは薄型表示装置用電極構造体103が收容する、被検査対象である画素電極又はその画素電極に隣接する画素電極に対して、第2の信号111をパルス電圧として印加する。

【0020】更に、制御部107は、検査部101に対して、検査対象となる画素電極の検査開始命令を示す第3の信号113を出力する。後述するが、検査部101が收容する複数の電位センサを個々に動作させる為、バイアス電圧として第3の信号113を印加する。

【0021】駆動部105は、制御部107からの第1の信号109にตอบสนองして、検査部101と薄型表示装置用電極構造体103とを、画素電極の配置に関して1行又は1列分だけ相対的に移動させる。

【0022】検査部101は、制御部107からの第3の信号113にตอบสนองして、各画素電極毎の検査報告を示す第4の信号を出力する。検査部101には、複数の電界効果トランジスタ(FET)機能を利用した電位センサが複数個設けられている。画素電極の具体的な検査については後述する。

【0023】次に、本発明の薄型表示装置用電極構造体の検査装置における、検査部101について、図2

(a)にその構成を示す。図1を参照しつつ、図2

(a)を参照して、本構成は、基板201に高位部203と低位部205が形成されている。

【0024】高位部203には、電位センサ部207が形成されている。電位センサ部207は、FET機能を利用した複数の電位センサ1N( $N$ は整数で1~ $n$ の整数)が、矢印の $c$ 方向に1列に並び、アレイ状に配置された電位検出用のセンサである。

【0025】各電位センサ1Nは、図1に示した薄型表示装置用電極構造体103における1行又は1列分の各

(4)

特開2000-55964

5

6

画素電極に位置的に対向する事になる。そして、制御部107からの検査開始命令である、第3の信号113を受けて、位置対向する画素電極に生じる画素電圧の検出を行い、電位センサ信号2N(Nは整数で1~nの整数)を出力する。

【0026】低位部205には、アンプ部209が形成されている。アンプ部209は、複数のアンプ3N(Nは1~nの整数)から成る電圧増幅部である。1つのアンプ3Nは、1つの電位センサ1Nに対応して接続され、1つの電位センサ1Nからの電位センサ信号2Nを増幅してアンプ信号4Nを出力する。

【0027】更に、低位部205には、スキャナ211が設けられている。アンプ3Nの出力側端子は、スキャナ211に各々接続されており、アンプ信号4Nを受け、検査対象である画素電極の検査報告を示す第4の信号115を順次出力する。

【0028】尚、電位センサ1Nとアンプ3N、及びアンプ3Nとスキャナ211との間は、各々配線により電気的に接続されている。その配線は金属膜形成法により配線層として低位部205の面上に形成されている。

【0029】図2(a)に示した検査部101或いはその一部である電位センサ部1Nを、図1における、検査対象である液晶パネルと一定間隔(第1の間隔d)に保持させながら走査し、検査報告を順次出力する事により、液晶パネルが収容する総画素電極を検査する事が可能となる。その際には、図1に示す矢印のa方向又はb方向と、図2(a)に示す矢印のc方向(第1の方向)とを一致させる事になる。

【0030】図3に、図2(a)に示した電位センサ部207による、薄型表示装置用電極構造体における画素毎の検査過程を示す。図1を参照しつつ、図3を参照して、本図は、薄型表示装置用電極構造体である液晶パネル6における1個の画素電極8と、電位センサ部207における1個の電位センサ1Nとの位置対向の様子を示している。

【0031】液晶パネル6は、ガラス基板7と画素電極8とから構成されている。画素電極8は、ガラス基板7の表面に形成されている。ここで、ガラス基板7と単位トランジスタ層5N(Nは整数で1~nの整数)間の間隔(第1の間隔d)は、20μm以下である。

【0032】この電位センサ1Nは、FET機能に応用したものであり、単位トランジスタ層5Nは、図2(a)における基板201の高位部203の表面に形成されている。単位トランジスタ層5Nには、ドレイン側電極D、ソース側電極S、ゲート側電極Gが形成されている。ドレイン側電極Dには、FET機能を実行する為の直流バイアス電圧である第3の信号113が制御部107から印加される。

【0033】本図において、制御部107からの被検査命令を示す第2の信号111を画素電極8に印加した場

合、画素電極8が断線していなければ、画素電極8に一定値の画素電圧が生じる。

【0034】ここで、制御部107から電位センサ1Nに、検査開始命令を示す第3の信号113が印加されている事で、FET機能を利用して、ドレイン側電極Dとソース側電極Sの間に電流(電位センサ信号2N)が生じる。

【0035】これは、ゲート側電極Gにより、該電位センサと位置対向する画素電極と、間隔dに従う空間において、静電容量Cを介して静電的に接続される事による。これにより、画素電圧を検出して電位センサ信号2Nが出力される。その時の電圧値又は電流値が、図2(a)におけるアンプ3Nで増幅され、スキャナ211から出力される。

【0036】本図では、1個の画素と1個の電位センサ1Nの関係を示しているが、次に、図2(a)に示すような、矢印のc方向(第1の方向)に配置される複数個の電位センサ1Nを用いた検査について説明する。

【0037】図1を参照しつつ、図2(a)を参照して、この場合、n行m列(n、mは整数)の行列要素として配置された画素電極を検査する為に、その1行又は1列分の複数の画素電極の各々にFET機能を有する電位センサ1Nを静電的に結合させる。その時、各々の画素電極に生じる画素電圧を電位センサ1Nが検出して、予め設定した閾値との間で検査異常の判定を行う。

【0038】尚、この検出機構は、画素電極との静電結合を可能にするFET機能を利用して、前記画素電極に生じる画素電圧を検出する為の1つ以上の電位センサ1Nからの電位センサ信号2Nを増幅する為のアンプ3Nに接続し、更にアンプ3Nをスキャナ211に接続されるものである。

【0039】この検査過程においては、検査対象である画素電極と位置対向する電位センサ1Nに対して、制御部107が、検査開始命令であり、バイアス電圧である第3の信号113を、順次切換を行って印加する事になる。又、制御部107は、検査対象である画素電極に対しても、被検査開始命令であり、パルス電圧である第2の信号を、順次切換を行って印加する事になる。これら動作の詳細は後述する。

【0040】尚、図3に示す、1個の画素に対応する検査部(簡易検査ユニット)を図2(b)に示す。本構成は、FET機能を利用した単一の電位センサ1Nと、単一のアンプ3Nからなる。

【0041】電位センサ1N及びアンプ3Nは、図2(a)に示したものと同一である。単一の電位センサ1Nは、該単一の電位センサ1Nと、位置対向する画素電極に生じる画素電圧を検出する為のゲート側電極Gにより、静電的に接続する事により、電位センサ信号2Nを出力する。アンプ3Nは、電位センサ信号2Nを増幅してアンプ信号4Nを出力する。

(5)

特開2000-55964

7

8

【0042】この簡易検査ユニットは、図1に示す薄型表示装置用電極構造体の部分的な検査（例えば、1行又は1列のみの領域を担当して検査する等）のみに係わらず、電圧を生じる物質（物体）に対して、非接触により電位検出する事が望まれる分野に適用する事も考えられる。

【0043】次に、本発明である、薄型表示装置用電極構造体の検査方法について説明する。始めに、図1に示す全体構成図を参照して、検査装置による検査方法の概要を説明する。

【0044】制御部107は、検査対象である画素電極に関する検査報告を示す第4の信号115に応答して、検査部101或いはその一部である電位センサ部207（図2（a））と、薄型表示装置用電極構造体103とが、画素電極の行列配置に関し、相対的に1行又は1列分だけ相対移動する為の命令を示す第1の信号109を出力する。

【0045】この第1の信号109を出力するタイミングは、制御部107は、画素電極の行列配置に関し、各1行又は各1列分（電位センサ部207が検査をする領域）の画素電極数に依存する所定の値になるまで、第4の信号115の入力回数をカウントし、所定の値に達した時点で第1の信号109を出力する。

【0046】駆動部105は、第1の信号109に応答して、検査部101或いはその一部である電位センサ部207と、薄型表示装置用電極構造体103とを、画素電極の行列配置に関し1行又は1列分だけ相対的に移動させる。

【0047】この相対的な移動については、画素電極間の距離と、相対移動速度とから決定される移動時間により、その移動の確認は実質的に把握できる。

【0048】そこで、制御部107は、相対的な移動が実行された時に、検査部101に対して検査開始命令を示す第3の信号113を出力する。前述したように（図3）、第3の信号113は、検査部101に収容される複数の電位センサ1Nを個々に動作させる為のバイアス電圧である。

【0049】又、制御部107は、薄型表示装置用電極構造体103において、検査対象となる画素電極に対し、被検査開始命令を示す第2の信号111を出力する。この第2の信号111は、試験用のパルス電圧である。

【0050】次に、図1を参照しつつ、図4以降を参照して、制御部107が、第3の信号113と、第2の信号111とを出力してから、検査部101からの第4の信号115に回答して、第1の信号109を出力する（次行又は次列に収容される画素電極の検査に移行する）までの動作の詳細を説明する。

【0051】図4に、薄型表示装置用電極構造体103として液晶パネル6と、電位センサ部207との検査過

程における上方からの位置関係を示す。本図では、検査部101の一部である電位センサ部207のみを表示している。

【0052】図4を参照して、液晶パネル6における画素電極は、縦横に行列配置されており、総画素数は $n \times m$ で、各画素電極は番地（NM）により示されている。ここで、Nは1からnの自然数であり、Mは1からmの自然数である。

【0053】電位センサ部207は、液晶パネル6と間隔d（例えば $20 \mu m$ 以内）を一定に保持した状態で、矢印のa方向に検査を実行しながら相対移動する。本図に示すように、画素電極（NM）はn行m列に行列配置しており、電位センサ部207の電位センサ（図示せず）は、液晶パネル6の縦一列の各画素電極に位置対向して収容されているものとしている。

【0054】図4における矢印のa方向と平行に切断した断面図を図5に示す。尚、図4及び図5においては、図1に示す制御部107からの第2の信号111及び第3の信号113、及び駆動部105との電気的及び機械的な連結について省略している。

【0055】次に、図6を用いて、図1に示す制御部107からの被検査命令に各画素電極が応答する動作を詳細に示す。尚本図においても、図4及び図5同様、制御部107からの第2の信号111及び第3の信号113、及び駆動部105との電気的及び機械的な連結については省略している。

【0056】図6を参照して、電位センサ部207は、矢印のa方向に関し、Mが1列目の位置に停止している。画素電極（11）～（n1）は、この電位センサ部207の各電位センサ要素11～1nに各々検査位置が対応している。

【0057】画素電極に対する具体的な検査手順を以下に示す。先ず、電位センサ21に、予め検査開始命令である第3の信号113を印加する。これにより電位センサ21のセンサ機能が待機状態となる。次に、電位センサ21に位置対向する画素電極（11）に、被検査命令である第2の信号111を印加する。

【0058】この時、電位センサ21が、画素電極（11）に生じる画素電圧を検出する事により、検査部101からの検査報告である第4の信号115が、図7

（a）に示すような出力電圧波形W1として検出できれば、画素電極（11）が正常であると判断する。この閾値との比較判断機能は検査部101及び制御部107内に設ける事等で対応できる。

【0059】仮に、図7（a）に示す出力波形W1が検出できない場合、即ち図7（b）に示すように、出力電圧が零である信号値を含めて、判定レベルを下回るような出力波形W0を検出すれば、その画素電極（11）は、断線状態にあると判断する。これが検査対象である画素電極（11）自身の断線検査である。

9

【0060】次に、画素電極(11)に隣接する画素電極との短絡検査を実行する。電位センサ21に第3の信号113を印加した状態で、画素電極(21)に第2の信号111を印加する。

【0061】この時、電位センサ21は、検査対象である画素電極(11)から画素電圧を検出し、検査部101からの検査報告である第4の信号115が、図7

(a)に示すような出力電圧波形W1として検出できれば、画素電極(11)と画素電極(21)は短絡状態にあると判断する。

【0062】仮に、図7(b)に示すように、判定レベルを下回る信号値を含めて、出力電圧が零であるような出力波形W0を検出すれば、画素電極(11)と画素電極(21)は短絡無しと判断する。

【0063】上述の検査手順と同様に、図6において、画素電極(11)に隣接する画素電極(12)と画素電極(22)についても第2の信号111を印加する事により、画素電極(11)と画素電極(12)間、及び画素電極(11)と画素電極(22)間の短絡状態を検査できる。

【0064】以上の検査方法により、画素電極(11)自身の断線の有無、及び画素電極(11)に隣接する画素電極間の短絡の有無の検査が可能となる。

【0065】又、この検査対象である画素電極(11)の検査の過程では、電位センサ21は、画素電極(11)に生じる画素電圧(図示せず)にตอบสนองして、電位センサ信号21(Nはこの場合1である)を出力する。

【0066】又、検査部101内において、アンプ31(Nはこの場合1である)は、電位センサ信号21を増幅して、アンプ信号41(Nはこの場合1である)を出力し、更にスキャナ211を介して、検査報告を示す第4の信号115として順次出力される。以上から、制御部107は、検査対象である画素電極(11)の検査の過程で、第4の信号115を4回カウントしている事になる。

【0067】即ち、制御部107が、検査対象である各画素電極単位の、第4の信号115の入力回数を予め表情報等で設定しておき、各画素電極に対応した入力回数と比較しながら、第4の信号115の入力回数を順次カウントする事により、次の検査対象である画素電極(21)の検査に移行する事が可能となる。この入力回数は、各画素電極が配置される位置に依存する。

【0068】次に、検査対象である画素電極(21)の検査を実行する。まず、制御部107は、画素電極(11)に関して、予め設定された入力回数(画素電極(11)では4回)に到達した事を確認して、検査対象である画素電極(21)の検査を実行する。

【0069】これは、制御部107が、先ず画素電極(21)に位置対向する電位センサ22に対して、第3の信号113を印加し、そして、画素電極(21)に対

(6)

特開2000-55964

10

して第2の信号111を印加する事である。

【0070】画素電極(11)の検査と同様に、検査対象である画素電極(21)の検査についても、画素電極(21)自身の断線の有無、及び画素電極(21)に隣接する画素電極間の短絡の有無の検査を実行する事になる。

【0071】上記検査を、図6に示す矢印のb方向n個の画素電極について実行する。ここで制御部107は、前述した画素電極単位の、第4の信号115の入力回数に加え、1列分(n個)の画素電極数(列単位)の、累積入力回数をカウントする。

【0072】そこで、列単位の累積入力回数を予め設定しておき、1列分の最後に入力する第4の信号115にตอบสนองして、電位センサ部207と液晶パネル6とが、1列分だけ相対的に移動させる為の第1の信号109を出力する。この列単位の累積入力回数は、先の各画素電極単位の入力回数を格納すべき表情報に追加する事等で対応できる。

【0073】上述した検査の手順は次の様になる。先ず、現在の検査対象である画素電極、又は該画素電極に隣接する画素電極は、第2の信号111に順次ตอบสนองして、検査対象である画素電極に順次画素電圧を生じさせる。

【0074】検査部101において、検査対象である画素電極に位置対向する電位センサは、前記第3の信号113にตอบสนองして、FET機能を利用して、静電結合により画素電圧を順次検出する。そして、検査部101において、検査対象である画素電極の検査報告を示す第4の信号115を順次出力する。

【0075】そこで、制御部107は、予め設定した画素電極単位の入力回数に従い、第4の信号115にตอบสนองして、次の検査対象である画素電極、又は画素電極に隣接する画素電極に対して、第2の信号111を順次出力する。又、次の検査対象である画素電極に位置対向する電位センサに対しては、第3の信号113を出力する。

【0076】以上の手順を、列方向の画素電極に対して行い、予め設定した列単位の累積入力回数に従い、第4の信号115にตอบสนองして、第1の信号109を出力して、駆動部105を動作させる事で、次の列に収容される画素電極の検査に移行する。

【0077】本検査手順により、検査部101或いはその一部である電位センサ部207を、矢印のa方向に走査する事で、総画素電極数 $n \times m$ 個を収容する液晶パネル6を検査する事が可能となる。

【0078】尚、本実施の形態では、検査対象である画素電極の短絡検査において重複を含んでいるが、短絡検査における重複を避けるような検査を実行する事も可能である。

【0079】これは例えば、検査対象である画素電極(11)の短絡検査の際に、画素電極(21)にパルス

特開2000-55964

12

* 101	:	検査部
103	:	薄型表示装置用電極構造体
105	:	駆動部
107	:	制御部
109	:	第1の信号
111	:	第2の信号
113	:	第3の信号
115	:	第4の信号
d	:	間隔〈第1の間隔〉
0 201	:	基板
203	:	高位部
205	:	低位部
207	:	電位センサ部
209	:	アンプ部
211	:	スクヤナ

1 N (Nは1～nの整数) : 電位センサ  
2 N (Nは1～nの整数) : 電位センサ信号  
3 N (Nは1～nの整数) : アンプ  
4 N (Nは1～nの整数) : アンプ信号  
5 N (Nは1～nの整数) : 単位トランジスタ層  
6 : 液晶パネル  
7 : ガラス基板  
8 (又は(NM)、Nは1～nの整数、Mは1～mの整数)  
: 画素電極  
C : 静電容量  
D : ドレイン側電極  
S : ソース側電極  
G : ゲート側電極  
P : P型半導体  
N (又はn) : N型半導体  
80 : TFTトランジスタ群の要素  
81、82 : 触針  
83 : ゲート電圧配線  
84 : 画素電極  
85 : ソース電圧配線  
86 : 基板

\*

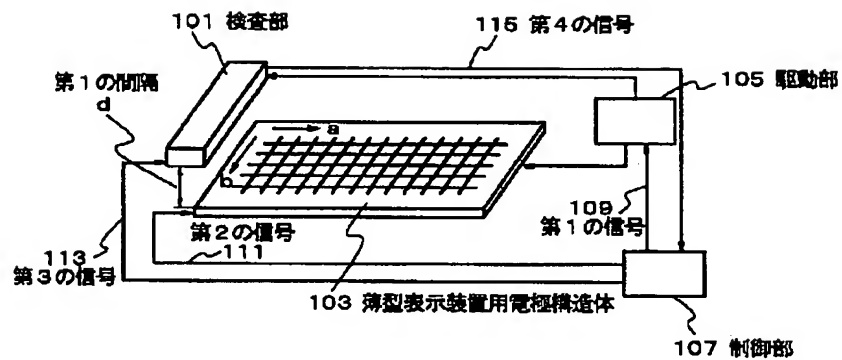
【图 5】



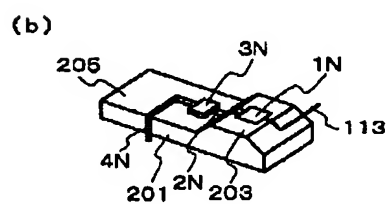
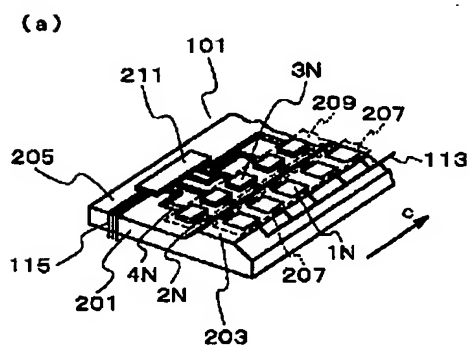
(8)

特開2000-55964

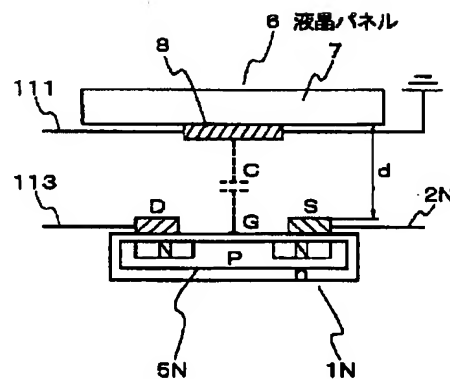
【図1】



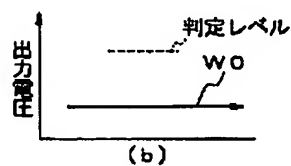
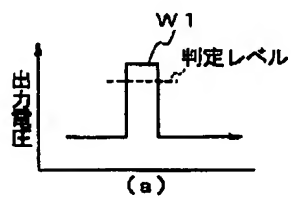
【図2】



【図3】



【図7】

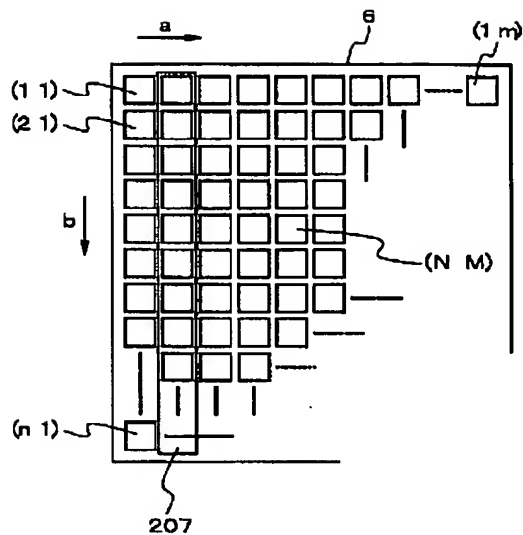




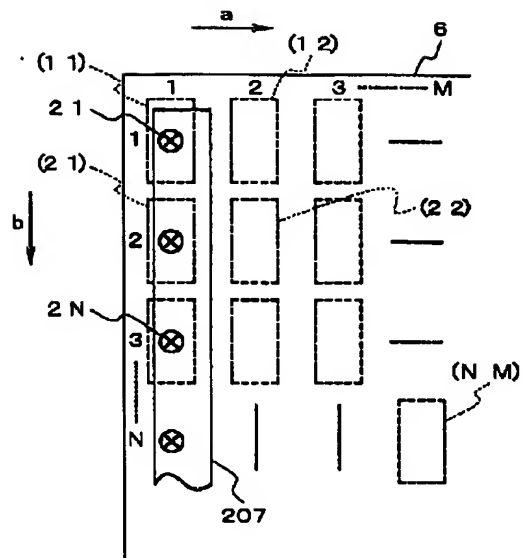
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特開2000-55964

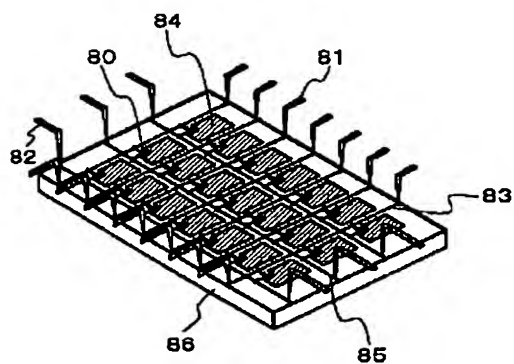
【図4】



【図6】



【図8】



フロントページの続き

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Page 1 of 2

## PATENT ABSTRACTS OF JAPAN

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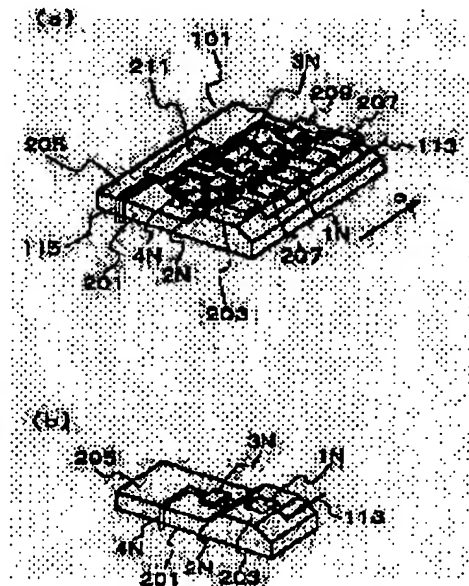
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### (54) DEVICE AND METHOD FOR INSPECTING ELECTRODE STRUCTURAL BODY FOR THIN-TYPE DISPLAY DEVICE

#### (57)Abstract:

**PROBLEM TO BE SOLVED:** To speed up an inspection and to make inspection highly accurate by electrostatically coupling a potential sensor to each of a plurality of pixel electrodes, detecting pixel voltage generated at each pixel electrode, and determining anomalies of the pixel electrodes on the basis of the detected pixel voltage.

**SOLUTION:** For performing inspection through the use of a plurality of potential sensors 1N arranged along the arrow (c), the potential sensors 1N with FET function are each electrostatically coupled to one row or one column of plurality of pixel electrodes arranged as the elements of a matrix with n-rows and m-columns. The potential sensors 1N detects pixel voltage generated at the pixel electrodes and determines inspection anomalies with respect to a threshold value set in advance. Potential sensor signals 2N from the electric sensors 1N are connected to amplifiers 3N for amplification, and further the amplifiers 3N are connected to a scanner 211. A control part 107 sequentially switches and impresses the third signal 113, which is a command to



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Page 2 of 2

start inspection and is bias voltage, on the potential sensors IN. age The control part 107 impresses the second signal on the pixel electrodes as well.

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JP,2000-055964,A [CLAIMS]

Page 1 of 2

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**CLAIMS**

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**[Claim(s)]**

[Claim 1] The inspection approach of the electrode structure for thin displays which detects the pixel electrical potential difference which is made to carry out the electrostatic coupling of the potential sensor which has field-effect transistor ability to each of two or more pixel electrodes, and is produced in said each electrode of a pixel, and is characterized by judging the abnormalities of said pixel electrode based on said detected pixel electrical potential difference.

[Claim 2] Test equipment which enforces the inspection approach of the electrode structure for thin displays according to claim 1 characterized by connecting to amplifier one or more potential sensors which detect the pixel electrical potential difference produced in said pixel electrode using the electric field effect TORAJISUTA function which carries out an electrostatic coupling to a pixel electrode, and coming to connect said amplifier with a scanner.

[Claim 3] In the Banking Inspection Department for inspecting the electrode structure for thin displays, and said Banking Inspection Department Two or more potential sensors using an FET function are arranged, and answer the 1st signal, and where the 1st spacing is held, said electrode structure for thin displays, and said some of Banking Inspection Department [ at least ] The mechanical component for making it move relatively and said electrode structure for thin displays about arrangement of a pixel electrode Said pixel electrode by which matrix arrangement is carried out is held in a n line m train (n and m are the natural number). Moreover, the orientation of two or more of said potential sensors, The line or the direction of a train in said matrix arrangement of said pixel electrode is in agreement, and the 4th signal which shows the inspection report of the pixel electrode which is a subject of examination is answered. The 2nd signal which outputs said 1st signal, and indicates an inspected initiation instruction to be said electrode structure for thin displays when said some of Banking Inspection Department [ at least ] moves relatively by one line or 1 train, Consist of the control section for outputting the 3rd signal which shows an inspection initiation instruction, and the pixel electrode which is the present subject of examination, or the pixel electrode contiguous to said pixel electrode by carrying out a sequential response to said 2nd signal Produce a pixel electrical potential difference one by one in said pixel electrode which is the present subject of examination, and the present potential sensor which carries out location opposite answers said pixel electrode which is said present subject of examination at said 3rd signal. Carry out sequential detection of said pixel electrical potential difference using an electrostatic coupling, carry out the sequential output of said 4th signal which shows the inspection report of the pixel electrode which is the present subject of examination, and said control section answers said 4th signal. Test equipment of the electrode structure for thin displays characterized by outputting said 2nd signal to the pixel electrode which is degree subject of examination, or the pixel electrode contiguous to said pixel electrode, and outputting said 3rd signal to the pixel electrode which is said degree subject of examination to the potential sensor which carries out location opposite.

[Claim 4] It is test equipment of the electrode structure for thin displays characterized by to consist of the amplifier for said potential sensor being equipped with the gate electrode for detecting the pixel electrical potential difference produced in a pixel electrode, and outputting a potential sensor signal to

JP,2000-055964,A [CLAIMS]

Page 2 of 2

the potential sensor using an FET function, and here by connecting electrostatic [ which carry out location opposite with this potential sensor / the pixel electrode and electrostatic ], amplifying said potential sensor signal, and outputting an amplifier signal.

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[Translation done.]

JP,2000-055964,A [DETAILED DESCRIPTION]

Page 1 of 8

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**DETAILED DESCRIPTION**

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**[Detailed Description of the Invention]****[0001]****[Field of the Invention]** This invention relates to the test equipment to the electrode structure for thin displays, and its inspection approach.**[0002]****[Description of the Prior Art]** The thin indicating equipment is produced considering the display of TV, a personal computer, etc. as the application. As the evaluation approach for the electrode structure for these thin displays, a performance test, a reliability trial, an appearance test, etc. occur. Especially about the conventional lighting actuation verification test, it carries out after assembly \*\*\*\* as a product.**[0003]** The inspection approach of the conventional electrode structure for thin displays is shown in drawing 8. In this conventional example, the liquid crystal panel is made into the example for the electrode structure for thin displays. In addition, the electrode structure for thin displays defines this specification as what holds the pixel electrode arranged as a matrix element of a n line m train (n and m are an integer).**[0004]** The inspection approach shown in drawing 8 is called a prober method. The gate voltage wiring 83 is formed on the substrate 86. These are formed in all directions between the elements 80 of a TFT mold transistor group, and are arranged.**[0005]** This inspection approach contacts sensing pins (prober) 81 and 82 to the source electrical-potential-difference wiring 85 respectively, and inspects an open circuit of the pixel electrode 84, a short circuit, etc. by detecting the output voltage. That is, the defect of the pixel electrode 84 is detected by impressing an inspection signal to the gate voltage wiring 83 currently formed in the electrode structure for thin displays, and the source electrical-potential-difference wiring 85.**[0006]****[Problem(s) to be Solved by the Invention]** The inspection approach of this prober method is faced with the problem that the number of poor contacts of a sensing pin increases, that exchange frequency increases with enlargement of the electrode structure for thin displays, and a sustaining cost increases as a result.**[0007]** A liquid crystal display is combined with the enlargement and full-color-izing accompanying many quantification of the display information, and also its highly minute-ization, and contraction-ization of a pixel pitch is demanded. Therefore, the test equipment which the poor contact of test equipment does not occur but enables a high speed and highly precise inspection, and its inspection approach are wanted to offer immediately.**[0008]** The purpose of this invention is to offer the test equipment and its inspection approach of the electrode structure for thin displays which enables improvement in the speed and highly-precise-izing of inspection.**[0009]****[Means for Solving the Problem]** In order to solve the above-mentioned technical problem, the test equipment and its inspection approach of the electrode structure for thin displays of this invention detect

the pixel electrical potential difference which is made to carry out the electrostatic coupling of the potential sensor which has field-effect transistor ability to each of two or more pixel electrodes, and is produced in said each electrode of a pixel, and are characterized by judging the abnormalities of said pixel electrode based on said detected pixel electrical potential difference.

[0010] Moreover, it is characterized by connecting to amplifier one or more potential sensors which detect the pixel electrical potential difference produced in said pixel electrode using the electric field effect TORAJISUTA function which carries out an electrostatic coupling to a pixel electrode, and coming to connect said amplifier with a scanner.

[0011] furthermore, in the Banking Inspection Department for inspecting the electrode structure for thin displays, and said Banking Inspection Department Two or more potential sensors using an FET function are arranged, and answer the 1st signal, and where the 1st spacing is held, said electrode structure for thin displays, and said some of Banking Inspection Department [ at least ] The mechanical component for making it move relatively by one line or 1 train and said electrode structure for thin displays about arrangement of a pixel electrode Said pixel electrode by which matrix arrangement is carried out is held in a n line m train (n and m are the natural number). Moreover, the orientation of two or more of said potential sensors, The line or the direction of a train in said matrix arrangement is in agreement, and the 4th signal which shows the inspection report of the pixel electrode which is a front subject of examination is answered. The 2nd signal which shows an inspected initiation instruction when said 1st signal is outputted and said electrode structure for thin displays and said some of Banking Inspection Department [ at least ] move relatively, Consist of the control section for outputting the 3rd signal which shows an inspection initiation instruction, and the pixel electrode which is the present subject of examination, or the pixel electrode contiguous to said pixel electrode by carrying out a sequential response to said 2nd signal Produce a pixel electrical potential difference one by one in said pixel electrode which is the present subject of examination, and the present potential sensor answers said 3rd signal in said Banking Inspection Department. Carry out sequential detection of said pixel electrical potential difference using an electrostatic coupling, carry out the sequential output of said 4th signal which shows the inspection report of the pixel electrode which is the present subject of examination, and said control section answers said 4th signal. It is characterized by being characterized by outputting said 2nd signal to the pixel electrode which is degree subject of examination, or the pixel electrode contiguous to said pixel electrode, and outputting said 3rd signal to the pixel electrode which is said degree subject of examination to the potential sensor which carries out location opposite.

[0012] Furthermore, it is characterized by to consist of the amplifier for said potential sensor being equipped with the gate electrode for detecting the pixel electrical potential difference produced in said pixel electrode, and outputting a potential sensor signal to the potential sensor using an FET function, and here by connecting electrostatic [ which carry out location opposite with this potential sensor / the pixel electrode and electrostatic ], amplifying said potential sensor signal here, and outputting an amplifier signal to them.

[0013]

[Embodiment of the Invention] Next, the test equipment and its inspection approach of the electrode structure for thin displays of this invention are explained to a detail with reference to an accompanying drawing. The gestalt of operation of the test equipment of the electrode structure for thin displays which is this invention is shown in drawing 1. In addition, the gestalt of operation of this invention explains a liquid crystal panel for the electrode structure for thin displays to an example.

[0014] With reference to drawing 1, this configuration consists of the Banking Inspection Department 101, and the mechanical component 105 and control section 107 for inspecting the electrode structure 103 for thin displays. The Banking Inspection Department 101 holds the electrode structure 103 for thin displays, and spacing d (the 1st spacing), and is stationed.

[0015] The electrode structure 103 for thin displays has held the pixel electrode arranged as a matrix element of a n line m train (n and m are an integer) (in drawing 1, matrix arrangement is carried out in the direction of a of an arrow head, and the direction of b of an arrow head).

[0016] A control section 107 answers the 4th signal 115 which shows the inspection report of each pixel



electrode which is a subject of examination from the Banking Inspection Department 101, and outputs the 1st signal 109 for the Banking Inspection Department 101 and the electrode structure 103 for thin displays to make it move relatively by one line or 1 train about matrix arrangement of a pixel electrode.

[0017] Although mentioned later, this corresponds, when a control section 107 counts the count of an input of the 4th signal 115 related to one line or the number of pixel electrodes for one train.

[0018] Moreover, a control section 107 gives the 2nd signal 111 which shows an inspected initiation instruction to the electrode structure 103 for thin displays, when the Banking Inspection Department 101 and the electrode structure 103 for thin displays move relatively by one line or 1 train.

[0019] Although mentioned later, this impresses the 2nd signal 111 as a pulse voltage to the pixel electrode contiguous to the pixel electrode which the electrode structure 103 for thin displays holds and which is an inspected object, or its pixel electrode.

[0020] Furthermore, a control section 107 outputs the 3rd signal 113 which shows the inspection initiation instruction of the pixel electrode used as a subject of examination to the Banking Inspection Department 101. Although mentioned later, in order to operate separately two or more potential sensors which the Banking Inspection Department 101 holds, the 3rd signal 113 is impressed as bias voltage.

[0021] A mechanical component 105 answers the 1st signal 109 from a control section 107, and moves relatively the Banking Inspection Department 101 and the electrode structure 103 for thin displays by one line or 1 train about arrangement of a pixel electrode.

[0022] The Banking Inspection Department 101 answers the 3rd signal 113 from a control section 107, and outputs the 4th signal which shows the inspection report for every pixel electrode. Two or more potential sensors using two or more field-effect transistor (FET) functions are prepared for the Banking Inspection Department 101. About a concrete inspection of a pixel electrode, it mentions later.

[0023] Next, the configuration is shown in drawing 2 (a) about the Banking Inspection Department 101 in the test equipment of the electrode structure for thin displays of this invention. With reference to drawing 2 (a), as for this configuration, the high order section 203 and the lower order section 205 are formed in the substrate 201, referring to drawing 1.

[0024] The potential sensor section 207 is formed in the high order section 203. The potential sensor section 207 is a sensor for potential detection by which two or more potential sensor 1Ns (N is the integer of 1 - n at an integer) using an FET function have been arranged a list and in the shape of an array in the direction of c of an arrow head at one train.

[0025] Each potential sensor 1N, one line or each pixel electrode for one train in the electrode structure 103 for thin displays shown in drawing 1 will be countered in location. And the pixel electrical potential difference which is the inspection initiation instruction from a control section 107 and which is produced in response to the 3rd signal 113 in the pixel electrode which carries out location opposite is detected, and 2 Ns (N is the integer of 1 - n at an integer) of potential sensor signals are outputted.

[0026] The amplifier section 209 is formed in the lower order section 205. The amplifier section 209 is the voltage amplification section which consists of two or more amplifier 3Ns (integer of N1-n). One amplifier 3N, it connects corresponding to one potential sensor 1N, 2 Ns of potential sensor signals from one potential sensor 1N are amplified, and 4 Ns of amplifier signals are outputted.

[0027] Furthermore, the scanner 211 is formed in the lower order section 205. It connects with the scanner 211 respectively, and an amplifier 3N output side terminal receives 4 Ns of amplifier signals, and carries out the sequential output of the 4th signal 115 which shows the inspection report of the pixel electrode which is a subject of examination.

[0028] In addition, wiring connects electrically respectively between potential sensor 1N, amplifier 3N and amplifier 3N, and a scanner 211. The wiring is formed on the field of the lower order section 205 as a wiring layer by the metal membrane forming method.

[0029] It scans making 1 N of potential sensor sections which are the Banking Inspection Department 101 which showed drawing 2 (a), or its part hold at the liquid crystal panel and fixed spacing (the 1st spacing d) in drawing 1 which are a subject of examination, and it becomes possible to inspect the total pixel electrode with which a liquid crystal panel holds an inspection report by carrying out a sequential output. In that case, the direction of a of an arrow head or the direction of b shown in drawing 1, and the

direction (the 1st direction) of c of the arrow head shown in drawing 2 (a) are made in agreement.

[0030] The inspection process for every pixel in the electrode structure for thin displays by the potential sensor section 207 shown in drawing 3 at drawing 2 (a) is shown. With reference to drawing 3, this Fig. shows signs (one pixel electrode 8 in the liquid crystal panel 6 which is the electrode structure for thin displays, and potential sensor of one piece 1N in the potential sensor section 207) that location opposite is carried out, referring to drawing 1.

[0031] The liquid crystal panel 6 consists of a glass substrate 7 and a pixel electrode 8. The pixel electrode 8 is formed in the front face of a glass substrate 7. Here, spacing (the 1st spacing d) between a glass substrate 7 and 5Ns (N is the integer of 1 - n at an integer) of unit transistor layers is 20 micrometers or less.

[0032] This potential sensor 1N, an FET function is applied and 5 Ns of unit transistor layers are formed in the front face of the high order section 203 of the substrate 201 in drawing 2 (a). The drain lateral electrode D, the source lateral electrode S, and the gate lateral electrode G are formed in 5Ns of unit transistor layers. The 3rd signal 113 which is the direct-current bias voltage for performing an FET function is impressed to the drain lateral electrode D from a control section 107.

[0033] In this Fig., if the pixel electrode 8 is not disconnected when the 2nd signal 111 which shows the inspected instruction from a control section 107 is impressed to the pixel electrode 8, the pixel electrical potential difference of constant value arises in the pixel electrode 8.

[0034] Here, a current (2Ns of potential sensor signals) arises from a control section 107 between the drain lateral electrode D and the source lateral electrode S using an FET function by the 3rd signal 113 which shows an inspection initiation instruction being impressed to potential sensor 1N.

[0035] This is because it connects with the pixel electrode which carries out location opposite with this potential sensor with the gate lateral electrode G electrostatic through electrostatic capacity C in the space according to spacing d. Thereby, a pixel electrical potential difference is detected and 2 Ns of potential sensor signals are outputted. The electrical-potential-difference value or current value at that time is amplified by amplifier 3N in drawing 2 (a), and is outputted from a scanner 211.

[0036] This Fig. explains the inspection using two or more potential sensor 1Ns arranged in the direction (the 1st direction) of c of an arrow head as shown in drawing 2 (a), although one pixel and the potential sensor 1N relation of one piece are shown next.

[0037] In order to inspect the pixel electrode arranged in this case as a matrix element of a n line m train (n and m are an integer) with reference to drawing 2 (a), referring to drawing 1, potential sensor 1N which has an FET function is combined with each of those one line or two or more pixel electrodes for one train electrostatic. Then, potential sensor 1N detects the pixel electrical potential difference produced in each pixel electrode, and the abnormalities in inspection are judged between the thresholds set up beforehand.

[0038] In addition, this detection device is connected to amplifier 3N for amplifying 2 Ns of potential sensor signals from 1 potential sensor 1Ns or more for detecting the pixel electrical potential difference produced in said pixel electrode using the FET function which makes an electrostatic coupling with a pixel electrode possible, and amplifier 3N is further connected to a scanner 211.

[0039] In this inspection process, to potential sensor 1N which carries out location opposite with the pixel electrode which is a subject of examination, a control section 107 will perform a sequential change-over, and will impress the 3rd signal 113 which is an inspection initiation instruction and is bias voltage. Moreover, also to the pixel electrode which is a subject of examination, a control section 107 will perform a sequential change-over, and will impress the 2nd signal which is an inspected initiation instruction and is a pulse voltage. The detail of these actuation is mentioned later.

[0040] In addition, the Banking Inspection Department (simple test unit) corresponding to one pixel which shows drawing 3 is shown in drawing 2 (b). This configuration consists of single potential sensor 1N using an FET function, and single amplifier 3N.

[0041] Potential sensor 1N and amplifier 3N are the same as that of what was shown in drawing 2 (a). Single potential sensor 1N, 2 Ns of potential sensor signals are outputted by connecting electrostatic with the gate lateral electrode G for detecting the pixel electrical potential difference produced in the

pixel electrode which carries out location opposite with potential sensor 1N of this single. Amplifier 3N, 2Ns of potential sensor signals are amplified, and 4Ns of amplifier signals are outputted.

[0042] Applying to the field expected to carry out potential detection of this simple test unit according to non-contact to the matter (body) which produces an electrical potential difference only irrespective of a partial inspection (for example, the field of only one line or one train is taken charge of and inspected) of the electrode structure for thin displays shown in drawing 1 is also considered.

[0043] Next, the inspection approach of the electrode structure for thin displays which is this invention is explained. With reference to the whole block diagram shown in introduction and drawing 1, the outline of the inspection approach by test equipment is explained.

[0044] A control section 107 answers the 4th signal 115 which shows the inspection report about the pixel electrode which is a subject of examination, and outputs the 1st signal 109 which shows an instruction to displace relatively the potential sensor section 207 (drawing 2 (a)) which is the Banking Inspection Department 101 or its part, and the electrode structure 103 for thin displays by one line or 1 train about matrix arrangement of a pixel electrode.

[0045] When the timing which outputs this 1st signal 109 counts the count of an input of the 4th signal 115 and reaches a predetermined value until a control section 107 becomes a predetermined value depending on one line each or the number of pixel electrodes for one train each (field where the potential sensor section 207 inspects) about matrix arrangement of a pixel electrode, it outputs the 1st signal 109.

[0046] A mechanical component 105 answers the 1st signal 109, and moves relatively the potential sensor section 207 which is the Banking Inspection Department 101 or its part, and the electrode structure 103 for thin displays by one line or 1 train about matrix arrangement of a pixel electrode.

[0047] About this relative migration, the check of that migration can be substantially grasped by the transit time determined from pixel inter-electrode distance and a relative-displacement rate.

[0048] Then, a control section 107 outputs the 3rd signal 113 which shows an inspection initiation instruction to the Banking Inspection Department 101, when relative migration is performed. As mentioned above (drawing 3 R> 3), the 3rd signal 113 is the bias voltage for operating separately two or more potential sensor 1Ns held in the Banking Inspection Department 101.

[0049] Moreover, a control section 107 outputs the 2nd signal 111 which shows an inspected initiation instruction to the pixel electrode used as a subject of examination in the electrode structure 103 for thin displays. This 2nd signal 111 is a pulse voltage for a trial.

[0050] Next, referring to drawing 1, after a control section 107 outputs the 3rd signal 113 and the 2nd signal 111 with reference to drawing 4 or subsequent ones, the 4th signal 115 is answered from the Banking Inspection Department 101, and a detail of operation is explained until it outputs the 1st signal 109 (it shifts to inspection of the pixel electrode held in the next line or the following train).

[0051] The physical relationship from the upper part in an inspection process with the potential sensor section 207 is indicated to be a liquid crystal panel 6 to drawing 4 as the electrode structure 103 for thin displays. In this Fig., only the potential sensor section 207 which are some Banking Inspection Department 101 is displayed.

[0052] With reference to drawing 4, matrix arrangement of the pixel electrode in a liquid crystal panel 6 is carried out in all directions, the total number of pixels is nxm and each pixel electrode is shown by the address (NM). Here, N is the natural number of 1 to n, and M is the natural number of 1 to m.

[0053] The potential sensor section 207 is in the condition which held uniformly a liquid crystal panel 6 and spacing d (for example, less than 20 micrometers), and it is displaced relatively, performing inspection in the direction of a of an arrow head. As shown in this Fig., the pixel electrode (NM) is carrying out matrix arrangement at the n line m train, and the potential sensor (not shown) of the potential sensor section 207 should carry out location opposite, and shall be held in each pixel electrode of the vertical single tier of a liquid crystal panel 6.

[0054] The sectional view cut to the direction of a of an arrow head and parallel in drawing 4 is shown in drawing 5. In addition, in drawing 4 and drawing 5, it is omitting about the electric and mechanical connection to the 2nd signal 111 from a control section 107 shown in drawing 1, the 3rd signal 113, and

a mechanical component 105.

[0055] Next, the actuation in which each pixel electrode answers the inspected instruction shown in drawing 1 from a control section 107 is shown in a detail using drawing 6. Also in a \*\*\*\* Fig., it is omitting like drawing 4 and drawing 5 about the electric and mechanical connection to the 2nd signal 111 from a control section 107, the 3rd signal 113, and a mechanical component 105.

[0056] With reference to drawing 6, M has stopped the potential sensor section 207 in the location of eye one train about the direction of a of an arrow head. As for pixel electrode (11) - (n1), the inspection location supports respectively each potential sensor elements 11-1n of this potential sensor section 207.

[0057] The concrete inspection routine to a pixel electrode is shown below. First, the 3rd signal 113 which is an inspection initiation instruction beforehand is impressed to the potential sensor 21. Thereby, the sensor ability of the potential sensor 21 will be in a standby condition. Next, the 2nd signal 111 which is an inspected instruction is impressed to the potential sensor 21 at the pixel electrode (11) which carries out location opposite.

[0058] If the 4th signal 115 whose potential sensor 21 is an inspection report from the Banking Inspection Department 101 by detecting the pixel electrical potential difference produced in a pixel electrode (11) can detect as output voltage wave W1 as shown in drawing 7 (a) at this time, a pixel electrode (11) will judge that it is normal. The comparative judgment function with this threshold can respond by preparing in the Banking Inspection Department 101 and a control section 107 etc.

[0059] If output wave W0 in which output voltage is less than judgment level including the signal value which is zero is detected as shown in drawing 7 (b) when output wave W1 shown in drawing 7 (a) cannot be detected temporarily namely, it will be judged that the pixel electrode (11) is in an open-circuit condition. This is the own open-circuit inspection of a pixel electrode (11) which is a subject of examination.

[0060] Next, shunt evaluation with the pixel electrode contiguous to a pixel electrode (11) is performed. Where the 3rd signal 113 is impressed to the potential sensor 21, the 2nd signal 111 is impressed to a pixel electrode (21).

[0061] If detectable as output voltage wave W1 as detects a pixel electrical potential difference and the 4th signal 115 which is an inspection report from the Banking Inspection Department 101 shows to drawing 7 (a) from the pixel electrode (11) whose potential sensor 21 is a subject of examination at this time, it will be judged that a pixel electrode (11) and a pixel electrode (21) are in a short circuit condition.

[0062] If output wave W0 [ as / whose output voltage is zero ] including the signal value which is less than judgment level is detected as shown in drawing 7 (b), a pixel electrode (11) and a pixel electrode (21) will judge that he has no short circuit.

[0063] The short circuit condition between a pixel electrode (11) and a pixel electrode (12) and between a pixel electrode (11) and a pixel electrode (22) can be inspected by impressing the 2nd signal 111 in drawing 6 like above-mentioned inspection routine also about the pixel electrode (12) and pixel electrode (22) contiguous to a pixel electrode (11).

[0064] By the above inspection approach, inspection of the existence of an open circuit of the pixel electrode (11) itself and the existence of the pixel inter-electrode short circuit which adjoins a pixel electrode (11) is attained.

[0065] Moreover, in process of inspection of the pixel electrode (11) which is this subject of examination, the potential sensor 21 answers the pixel electrical potential difference (not shown) produced in a pixel electrode (11), and outputs the potential sensor signal 21 (N is 1 in this case).

[0066] Moreover, into the Banking Inspection Department 101, amplifier 31 (N is 1 in this case) amplifies the potential sensor signal 21, and outputs the amplifier signal 41 (N is 1 in this case), and a sequential output is further carried out through a scanner 211 as the 4th signal 115 which shows an inspection report. As mentioned above, a control section 107 is the process of inspection of the pixel electrode (11) which is a subject of examination, and will have counted the 4th signal 115 4 times.

[0067] That is, the control section 107 sets up beforehand the count of an input of the 4th signal 115 of each pixel electrode unit which is a subject of examination by expression news etc., and it becomes

possible by carrying out the sequential count of the count of an input of the 4th signal 115 to shift to inspection of the pixel electrode (21) which is the following subject of examination, comparing with the count of an input corresponding to each pixel electrode. It depends for this count of an input on the location where each pixel electrode is arranged.

[0068] Next, inspection of the pixel electrode (21) which is a subject of examination is performed. First, a control section 107 checks having reached the count of an input (a pixel electrode (11) 4 times) set up beforehand about a pixel electrode (11), and performs inspection of the pixel electrode (21) which is a subject of examination.

[0069] First, this impresses the 3rd signal 113 to the potential sensor 22 which carries out location opposite at a pixel electrode (21), and a control section 107 is impressing the 2nd signal 111 to a pixel electrode (21).

[0070] Inspection of the existence of an open circuit of the pixel electrode (21) itself and the existence of the pixel inter-electrode short circuit which adjoins a pixel electrode (21) will be performed about inspection of the pixel electrode (21) which is a subject of examination as well as inspection of a pixel electrode (11), and a case.

[0071] It performs about the pixel electrode of the n directions of b of the arrow head which shows the above-mentioned inspection to drawing 6. In addition to the count of an input of the 4th signal 115 of the pixel electrode unit mentioned above, a control section 107 counts the count of an accumulation input of the number of pixel electrodes (train unit) for one train (n pieces) here.

[0072] Then, the count of an accumulation input of a train unit is set up beforehand, the 4th signal 115 inputted into the last for one train is answered, and the potential sensor section 207 and a liquid crystal panel 6 output the 1st signal 109 for making it move relatively by one train. The count of an accumulation input of this train unit can respond by adding to the expression news which should store the count of an input of each previous pixel electrode unit etc.

[0073] The procedure of inspection mentioned above is as follows. First, the pixel electrode which is a current subject of examination, or the pixel electrode contiguous to this pixel electrode carries out a sequential response at the 2nd signal 111, and the pixel electrode which is a subject of examination is made to produce a pixel electrical potential difference one by one.

[0074] In the Banking Inspection Department 101, the potential sensor which carries out location opposite at the pixel electrode which is a subject of examination answers at said 3rd signal 113, and carries out sequential detection of the pixel electrical potential difference by the electrostatic coupling using an FET function. And in the Banking Inspection Department 101, the sequential output of the 4th signal 115 which shows the inspection report of the pixel electrode which is a subject of examination is carried out.

[0075] Then, according to the count of an input of the pixel electrode unit set up beforehand, a control section 107 answers the 4th signal 115, and carries out the sequential output of the 2nd signal 111 to the pixel electrode which is the following subject of examination, or the pixel electrode contiguous to a pixel electrode. Moreover, to the potential sensor which carries out location opposite, the 3rd signal 113 is outputted to the pixel electrode which is the following subject of examination.

[0076] The above procedure is performed to the pixel electrode of the direction of a train, and according to the count of an accumulation input of the train unit set up beforehand, the 4th signal 115 is answered, the 1st signal 109 is outputted, and it shifts to inspection of the pixel electrode held in the following train in operating a mechanical component 105.

[0077] This inspection routine enables it to inspect the liquid crystal panel 6 which holds the total number nxm individual of pixel electrodes by scanning the potential sensor section 207 which is the Banking Inspection Department 101 or its part in the direction of a of an arrow head.

[0078] In addition, although duplication is included with the gestalt of this operation in the shunt evaluation of the pixel electrode which is a subject of examination, it is also possible to perform inspection which avoids the duplication in shunt evaluation.

[0079] It is controlling not to perform impression of the pulse voltage to a pixel electrode (11) in the case of the shunt evaluation of the pixel electrode (21) which are after the shunt evaluation by this

JP,2000-055964,A [DETAILED DESCRIPTION]

Page 8 of 8

impressing a pulse voltage (the 2nd signal 111) to a pixel electrode (21) in the case of the shunt evaluation of the pixel electrode (11) which is a subject of examination, next a subject of examination. [0080] Moreover, although only the number corresponding to the pixel electrode for a vertical single tier in a liquid crystal panel 6 (n pieces) shall have held potential sensor 1N (integer of  $N1-n$ ) with the gestalt of this operation as the potential sensor section 207 is shown in drawing 4 or drawing 6 It is also possible to hold the potential sensor corresponding to the pixel electrode for a horizontal single tier (m pieces) similarly, and to inspect in the direction of b shown in drawing 6 . [0081] It is also possible to control by total pixel several n electrode xm to classify into two or more fields the field of the pixel electrode in a liquid crystal panel 6 by which matrix arrangement was carried out, to have only a number applicable to the field potential sensor section 207, and to scan only the field for inspection.

[0082]

[Effect of the Invention] The high speed and the highly precise inspection corresponding to enlargement of a thin display, full-color-izing, and highly-minute-izing are attained by the test equipment and its inspection approach of the electrode structure for thin displays which is this invention.

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[Translation done.]

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**DESCRIPTION OF DRAWINGS**

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**[Brief Description of the Drawings]**

**[Drawing 1]** Drawing 1 is the block diagram showing the test equipment of the electrode structure for thin indicating equipments by this invention.

**[Drawing 2]** Drawing 2 (a) is an isometric projection Fig. to show the Banking Inspection Department by this invention. Drawing 2 (b) is an isometric projection Fig. to show the Banking Inspection Department (simple unit) by this invention.

**[Drawing 3]** Drawing 3 is the sectional view showing a liquid crystal panel and some inspection approaches of the Banking Inspection Department.

**[Drawing 4]** Drawing 4 is the top view showing the physical relationship of a liquid crystal panel and the Banking Inspection Department.

**[Drawing 5]** Drawing 5 is the transverse-plane sectional view of drawing 4.

**[Drawing 6]** Drawing 6 is a top view for explaining the actuation which shows the inspection approach of the liquid crystal panel by this invention.

**[Drawing 7]** Drawing 7 (a) and (b) are graphs which show the example of a detection wave.

**[Drawing 8]** Drawing 8 is the isometric projection Fig. showing the conventional example.

**[Description of Notations]**

101 : Banking Inspection Department

103 : Electrode Structure for Thin Displays

105 : Mechanical Component

107 : Control Section

109 : 1st Signal

111 : 2nd Signal

113 : 3rd Signal

115 : 4th Signal

d : Spacing (the 1st spacing)

201 : Substrate

203 : High Order Section

205 : Lower Order Section

207 : Potential Sensor Section

209 : Amplifier Section

211 : Scanner

1N (integer of N1-n) : Potential sensor

2Ns (integer of N1-n) : Potential sensor signal

3Ns (integer of N1-n) : Amplifier

4Ns (integer of N1-n) : Amplifier signal

5Ns (integer of N1-n) : Unit transistor layer

6 : Liquid Crystal Panel

7 : Glass Substrate



· JP,2000-055964,A [DESCRIPTION OF DRAWINGS]

Page 2 of 2

8 Or M is (NM), Integer of N1-N, and Integer of 1-M.

: Pixel electrode

C : Electrostatic capacity

D : Drain lateral electrode

S : Source lateral electrode

G : Gate lateral electrode

P : P-type semiconductor

N (or n) : N-type semiconductor

80 : Element of TFT Transistor Group

81 82 : Sensing pin

83 : Gate Voltage Wiring

84 : Pixel Electrode

85 : Source Electrical-Potential-Difference Wiring

86 : Substrate

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[Translation done.]

JP,2000-055964,A [DRAWINGS]

Page 1 of 4

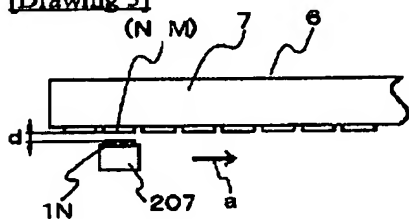
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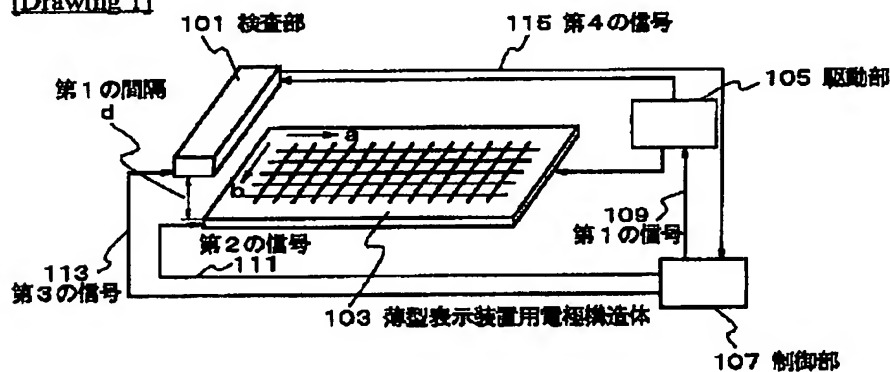
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## DRAWINGS

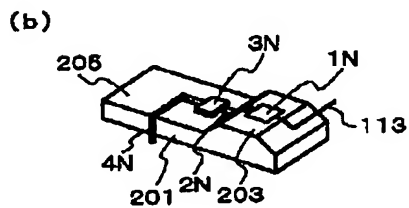
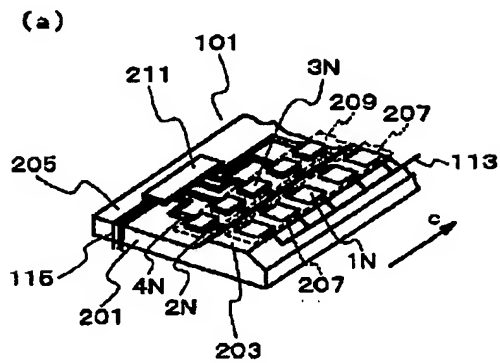
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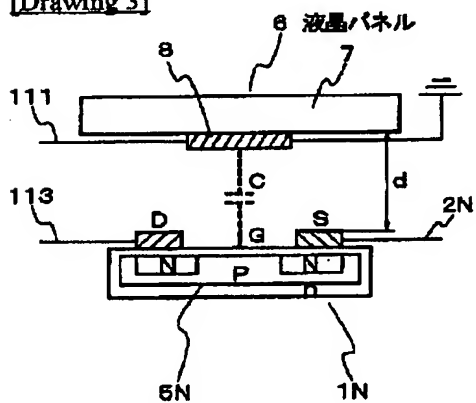
[Drawing 1]



[Drawing 2]



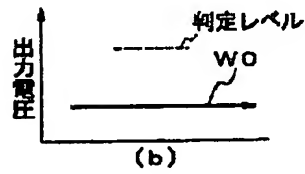
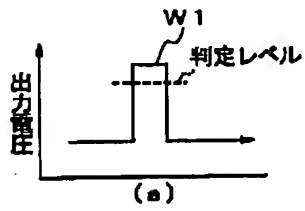
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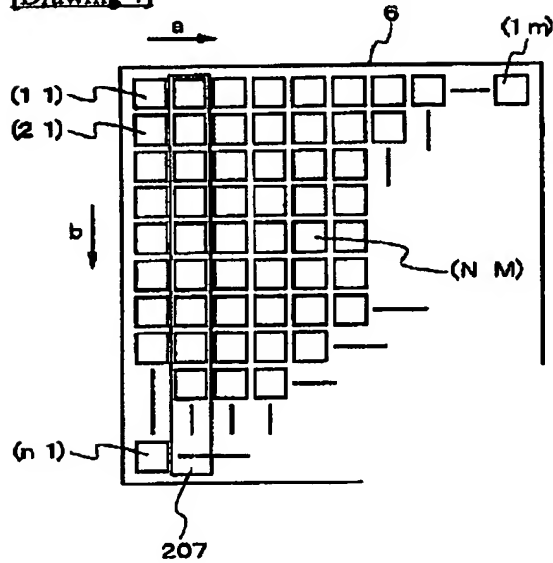
[Drawing 7]

JP,2000-055964,A [DRAWINGS]

Page 3 of 4



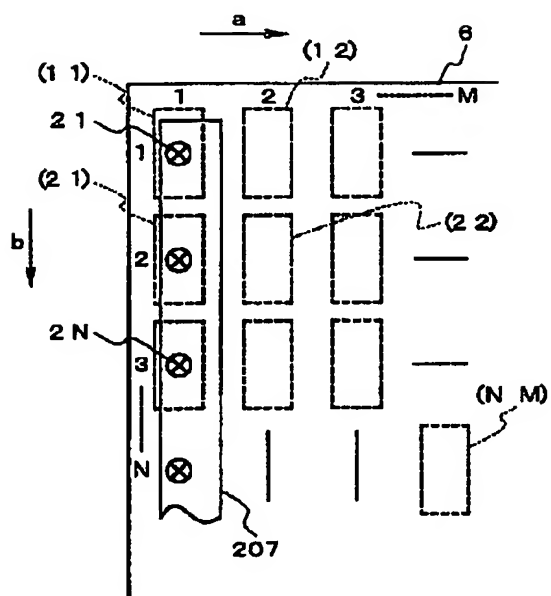
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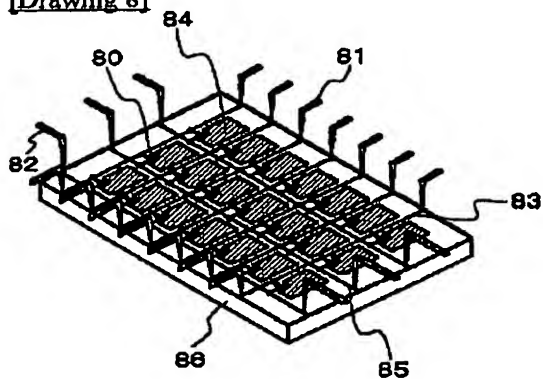
[Drawing 6]

JP,2000-055964,A [DRAWINGS]

Page 4 of 4



[Drawing 8]



[Translation done.]

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